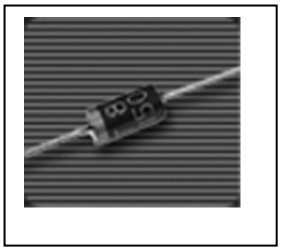
Glass Passivated Junction Rectifiers
Reverse Voltage 50V to 1000V Forward Current 2.0 Amperes



RL201G thru RL207G

Features

- Low forward voltage drop
- High current capability
- High reliability
- High surge current capability
- The plastic material carries UL recognition 94V-0

Mechanical Characteristics:

•Case: JEDEC DO-204AC(DO-15) molded plastic
•Terminals: Tin plated axial leads, solderable per MIL-STD-202E, method 208C
•Polarity: Color band denotes cathode
•Mounting position: Any
•High temperature soldering guaranteed : 250°C/10seconds, 0.375”(9.5mm) lead length at 5 lbs(2.3kg) tension
•Weight : 0.014oz., 0.39grams

Maximum Ratings and Electrical Characteristics

(Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%)

Parameter		Symbol	Type							Units
			RL201G	RL202G	RL203G	RL204G	RL205G	RL206G	RL207G	
Maximum Repetitive peak reverse voltage		V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage		V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage		V_{DC}	50	100	200	400	600	800	1000	V
Maximum instantaneous forward voltage I_F=2A		V_F	1.1							V
Maximum average forward rectified current, 0.375”(9.5mm) lead length at T_A=60°C		$I_{F(AV)}$	2							A
Peak forward surge current @8.3ms single half sine wave superimposed on rated load (JEDEC method)		I_{FSM}	55							A
Maximum DC reverse current at rated DC blocking voltage	T_A=25°C	I_R	5							μA
	T_A=125°C		100							
Typical junction capacitance (Note 1)		C_J	30							pF
Typical Thermal Resistance		$R_{\theta JA}$	40							°C/W
Storage temperature range		Tstg	-55 ~ +150							℃
Operating junction temperature range		T_J	-55 ~ +150							℃

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0VDC

Ratings and Characteristic Curves

FIG.1- TYPICAL FORWARD CHARACTERISTICS

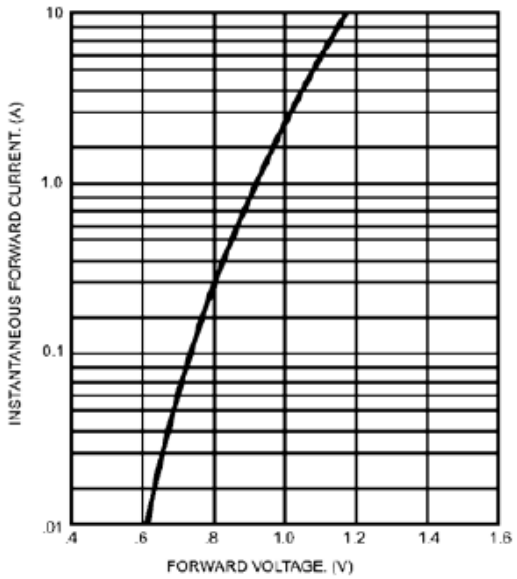


FIG.2- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

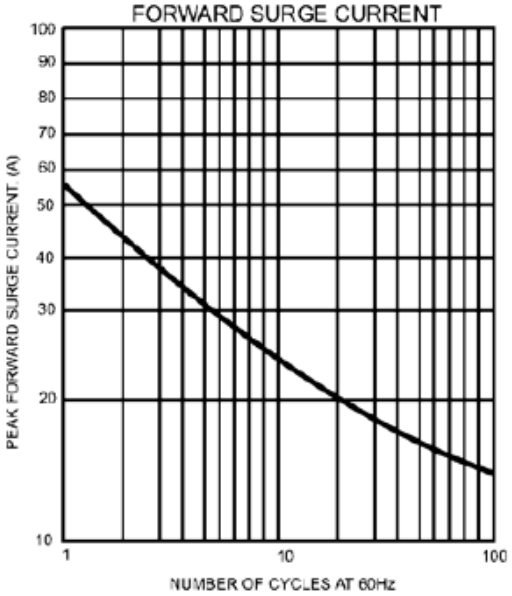


FIG.3- MAXIMUM FORWARD CURRENT DERATING CURVE

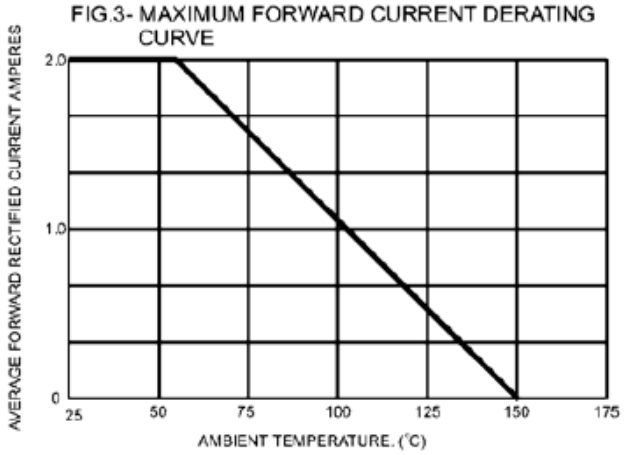
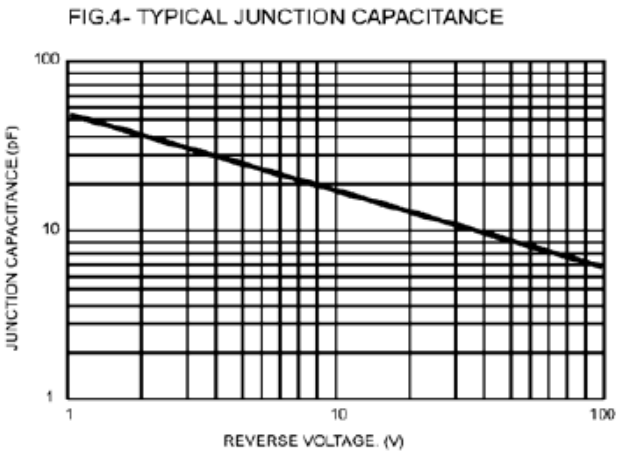
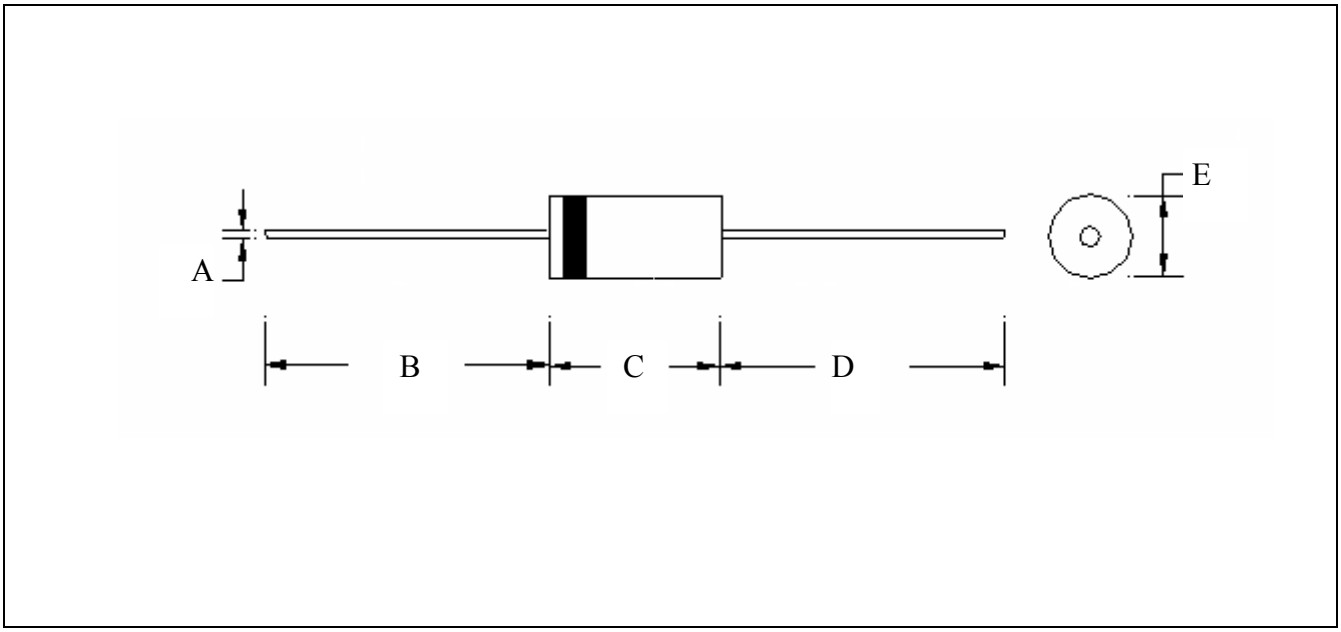


FIG.4- TYPICAL JUNCTION CAPACITANCE



DO-204AC(DO-15) Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	ϕ0.028	ϕ0.034	ϕ0.70	ϕ0.90	D	1.000	-	25.40	-
B	1.000	-	25.40	-	E	ϕ0.104	ϕ0.140	ϕ2.60	ϕ3.60
C	0.2300	0.3000	5.80	7.60					

Notes : 1.Controlling dimension : millimeters.
2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

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